

Title (en)

METHOD FOR MAKING A HEAT CONDUCTION-COOLED ELECTRONIC CARD

Title (de)

HERSTELLUNGSVERFAHREN EINER ELEKTRONISCHEN LEITERPLATTE MIT WÄRMEABLEITUNG

Title (fr)

PROCEDE DE FABRICATION D'UNE CARTE ELECTRONIQUE A REFROIDISSEMENT PAR CONDUCTION THERMIQUE

Publication

EP 0811309 A1 19971210 (FR)

Application

EP 96902303 A 19960130

Priority

- FR 9600150 W 19960130
- FR 9501972 A 19950221

Abstract (en)

[origin: WO9626631A1] Methods for making thermally cooled electronic cards are disclosed. The method comprises providing a card (2, 3i) of any kind to be covered with a rigid heat sink (1) shaped to fit and attached to the card (2, 3i), and forming said heat sink (1) in such a way that it fits as closely as possible the shape of the printed circuit (2) having components (3i) on one or both sides thereof, whereby the surface thermal coupling between the sink (1) and the card (2, 3i) may be increased, by means of an optical sensor which preferably operates with a laser beam. Such a heat sink may thus be manufactured more quickly.

IPC 1-7

H05K 7/20; **G05B 19/42**

IPC 8 full level

G05B 19/42 (2006.01); **H05K 7/20** (2006.01)

CPC (source: EP US)

G05B 19/4207 (2013.01 - EP US); **H05K 7/20509** (2013.01 - EP US); **G05B 2219/49347** (2013.01 - EP US); **Y02P 90/02** (2015.11 - EP US); **Y10T 29/4913** (2015.01 - EP US); **Y10T 29/49131** (2015.01 - EP US); **Y10T 29/53174** (2015.01 - EP US)

Citation (search report)

See references of WO 9626631A1

Designated contracting state (EPC)

DE FR GB IT

DOCDB simple family (publication)

WO 9626631 A1 19960829; CA 2212943 A1 19960829; EP 0811309 A1 19971210; FR 2730894 A1 19960823; FR 2730894 B3 19970314; US 6035524 A 20000314

DOCDB simple family (application)

FR 9600150 W 19960130; CA 2212943 A 19960130; EP 96902303 A 19960130; FR 9501972 A 19950221; US 89423397 A 19970821